

# XYLEX™ RESIN X8210

REGION AMERICAS

## DESCRIPTION

PC+POLYESTER alloy. Unreinforced, transparent, impact modified for low temperature ductility

## TYPICAL PROPERTY VALUES

Revision 20170913

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
<b>MECHANICAL</b>			
Tensile Stress, yld, Type I, 50 mm/min	43	MPa	ASTM D 638
Tensile Stress, brk, Type I, 50 mm/min	46	MPa	ASTM D 638
Tensile Strain, yld, Type I, 50 mm/min	5	%	ASTM D 638
Tensile Strain, brk, Type I, 50 mm/min	150	%	ASTM D 638
Tensile Modulus, 50 mm/min	1480	MPa	ASTM D 638
Flexural Stress, yld, 1.3 mm/min, 50 mm span	65	MPa	ASTM D 790
Flexural Modulus, 1.3 mm/min, 50 mm span	1600	MPa	ASTM D 790
Tensile Stress, yield, 50 mm/min	45	MPa	ISO 527
Tensile Stress, break, 50 mm/min	45	MPa	ISO 527
Tensile Strain, yield, 50 mm/min	4.6	%	ISO 527
Tensile Strain, break, 50 mm/min	>150	%	ISO 527
Tensile Modulus, 1 mm/min	1500	MPa	ISO 527
Flexural Stress, break, 2 mm/min	58	MPa	ISO 178
Flexural Modulus, 2 mm/min	1600	MPa	ISO 178
<b>IMPACT</b>			
Izod Impact, notched, 23°C	800	J/m	ASTM D 256
Izod Impact, notched, -20°C	640	J/m	ASTM D 256
Izod Impact, notched, -30°C	200	J/m	ASTM D 256
Instrumented Impact Total Energy, 23°C	81	J	ASTM D 3763
Izod Impact, notched 80*10*4 +23°C	45	kJ/m <sup>2</sup>	ISO 180/1A
Izod Impact, notched 80*10*4 -10°C	30	kJ/m <sup>2</sup>	ISO 180/1A
Izod Impact, notched 80*10*4 -30°C	11	kJ/m <sup>2</sup>	ISO 180/1A
Charpy 23°C, V-notch Edgew 80*10*4 sp=62mm	71	kJ/m <sup>2</sup>	ISO 179/1eA
<b>THERMAL</b>			
Vicat Softening Temp, Rate B/50	97	°C	ASTM D 1525
HDT, 0.45 MPa, 3.2 mm, unannealed	79	°C	ASTM D 648
HDT, 1.82 MPa, 3.2mm, unannealed	75	°C	ASTM D 648

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
CTE, -40°C to 40°C, flow	1.1E-04	1/°C	ASTM E 831
CTE, -40°C to 40°C, xflow	1.1E-04	1/°C	ASTM E 831
CTE, -40°C to 40°C, flow	8.3E-05	1/°C	ISO 11359-2
CTE, -40°C to 40°C, xflow	8.9E-05	1/°C	ISO 11359-2
Vicat Softening Temp, Rate B/50	92	°C	ISO 306
Vicat Softening Temp, Rate B/120	97	°C	ISO 306
HDT/Ae, 1.8 MPa Edgew 120*10*4 sp=100mm	82	°C	ISO 75/Ae
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	81	°C	ISO 75/Af
<b>PHYSICAL</b>			
Specific Gravity	1.2	-	ASTM D 792
Mold Shrinkage, flow, 3.2 mm (5)	0.5 – 0.8	%	SABIC method
Mold Shrinkage, xflow, 3.2 mm (5)	0.4 – 0.6	%	SABIC method
Melt Flow Rate, 265°C/2.16kgf	10	g/10 min	ASTM D 1238
Melt Flow Rate, 300°C/1.2 kgf	14	g/10 min	ASTM D 1238
Density	1.16	g/cm <sup>3</sup>	ISO 1183
Water Absorption, (23°C/sat)	0.37	%	ISO 62
Moisture Absorption (23°C / 50% RH)	0.15	%	ISO 62
Melt Volume Rate, MVR at 265°C/2.16 kg	10	cm <sup>3</sup> /10 min	ISO 1133
Melt Volume Rate, MVR at 300°C/1.2 kg	13	cm <sup>3</sup> /10 min	ISO 1133
<b>OPTICAL</b>			
Light Transmission, 2.54 mm	85	%	ASTM D 1003
Haze, 2.54 mm	4	%	ASTM D 1003
<b>INJECTION MOLDING</b>			
Drying Temperature	65 – 75	°C	
Drying Time	3 – 5	hrs	
Drying Time (Cumulative)	8	hrs	
Maximum Moisture Content	0.02	%	
Melt Temperature	245 – 265	°C	
Nozzle Temperature	245 – 265	°C	
Front - Zone 3 Temperature	245 – 265	°C	
Middle - Zone 2 Temperature	240 – 260	°C	
Rear - Zone 1 Temperature	240 – 250	°C	
Mold Temperature	45 – 60	°C	
Back Pressure	0.2 – 0.5	MPa	
Screw Speed	20 – 100	rpm	
Shot to Cylinder Size	40 – 80	%	
Vent Depth	0.013 – 0.02	mm	



## DISCLAIMER

Any sale by SABIC, its subsidiaries and affiliates (each a "seller"), is made exclusively under seller's standard conditions of sale (available upon request) unless agreed otherwise in writing and signed on behalf of the seller. While the information contained herein is given in good faith, SELLER MAKES NO WARRANTY, EXPRESS OR IMPLIED, INCLUDING MERCHANTABILITY AND NONINFRINGEMENT OF INTELLECTUAL PROPERTY, NOR ASSUMES ANY LIABILITY, DIRECT OR INDIRECT, WITH RESPECT TO THE PERFORMANCE, SUITABILITY OR FITNESS FOR INTENDED USE OR PURPOSE OF THESE PRODUCTS IN ANY APPLICATION. Each customer must determine the suitability of seller materials for the customer's particular use through appropriate testing and analysis. No statement by seller concerning a possible use of any product, service or design is intended, or should be construed, to grant any license under any patent or other intellectual property right.